

ABSTRACT OF THE DISCLOSURE

A method for forming a stackable wafer for use in an implantable device is provided.

- 5 The method comprises forming an opening extending substantially through the wafer. Thereafter, conductive material is deposited within the opening to substantially fill the opening. A bump is then formed on an upper surface of the wafer adjacent the conductive material, and a contact pad is formed on a lower surface of the wafer adjacent the conductive material. A second wafer formed using substantially the same process may then be stacked
- 10 on top of the first wafer with the bump of the first wafer being in contact with the contact pad of the second wafer. A soldering process may then be used to couple the adjacent pad and wafer for physically mounting the wafers and providing electrical connectivity therebetween.